Actron Technology

(8255.TT)

Investor Conference

Speakers:

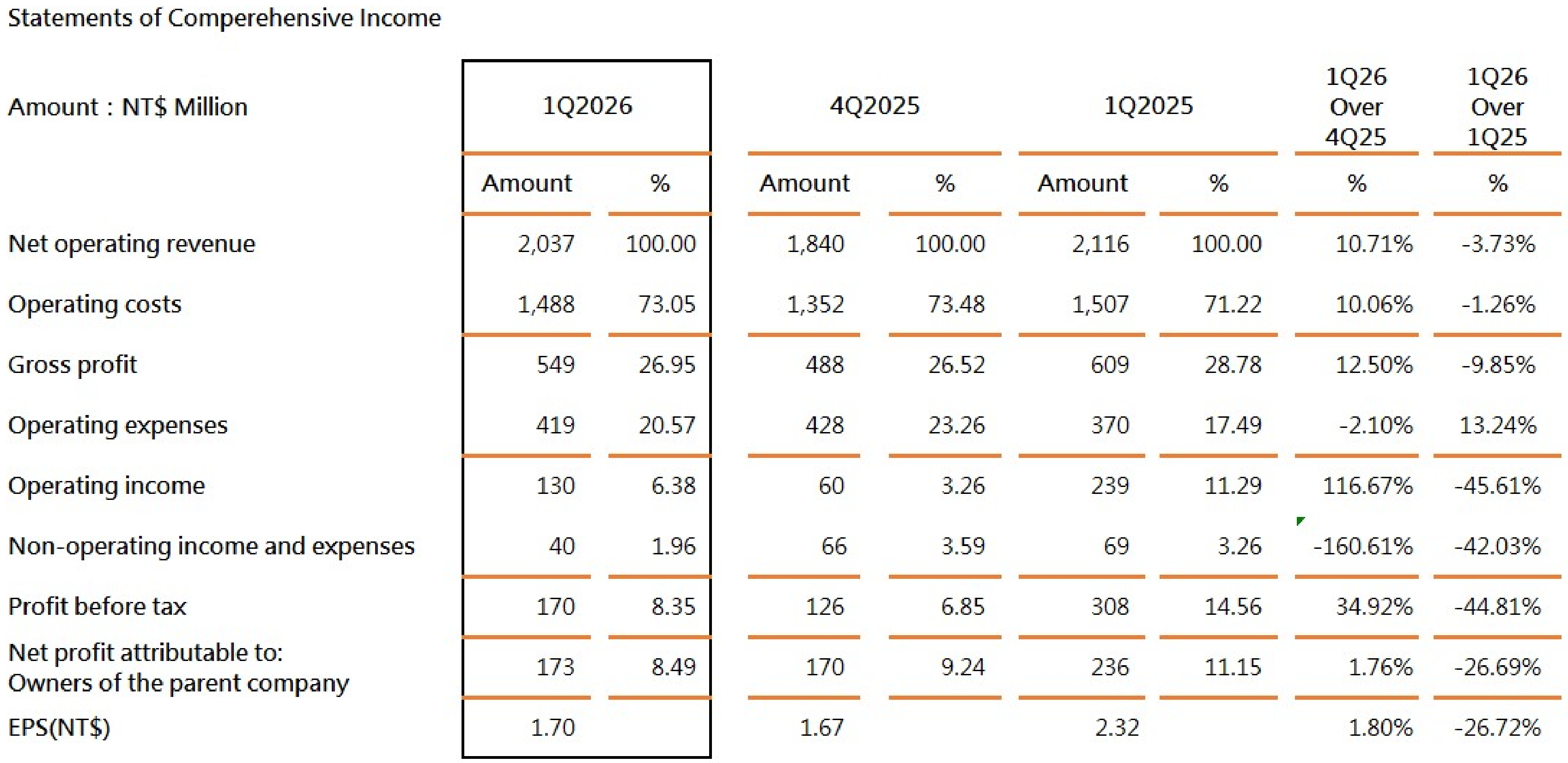
- 吳憲忠 George Wu: President / Spokesperson
- 黃錫欽 Jason Huang: VP of Sales & Marketing / Deputy Spokesperson
- 鍾曉瑩 Mia Chung：Special assistance / Investor Relations

May 26, 2026

Agenda

1. Financial Highlight
2. Global Automobile Sales
3. Q & A

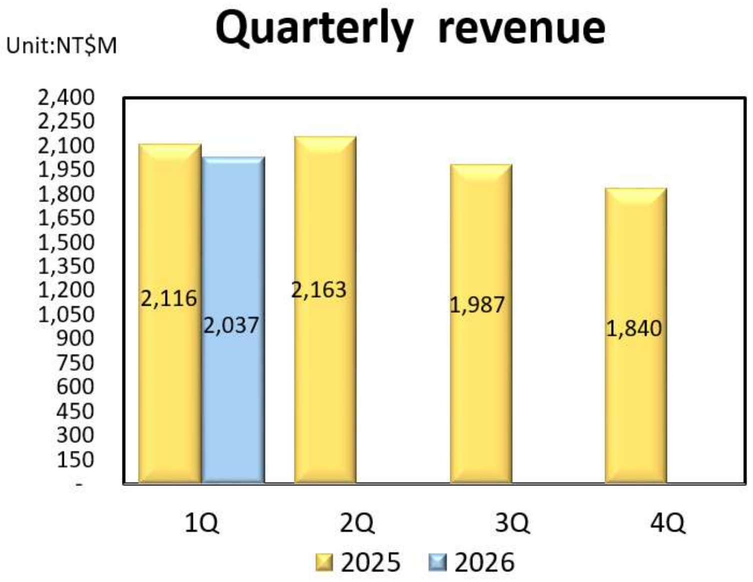
Statements of Comprehensive Income

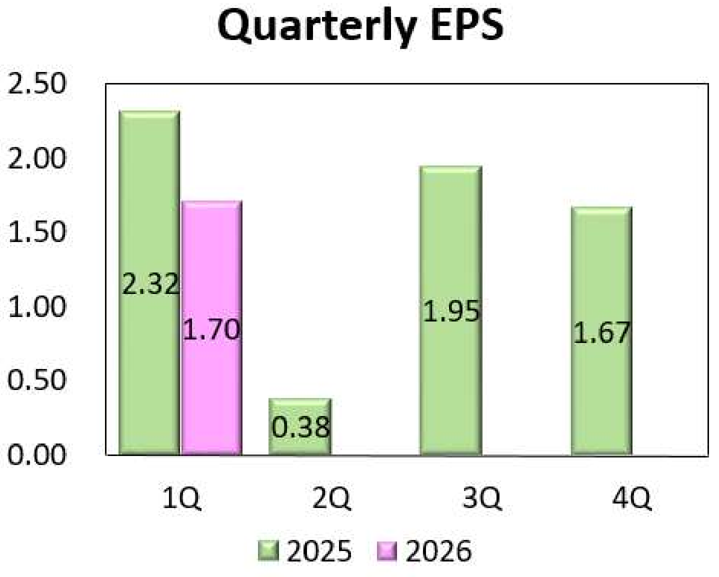


Statements of Comperehensive Income

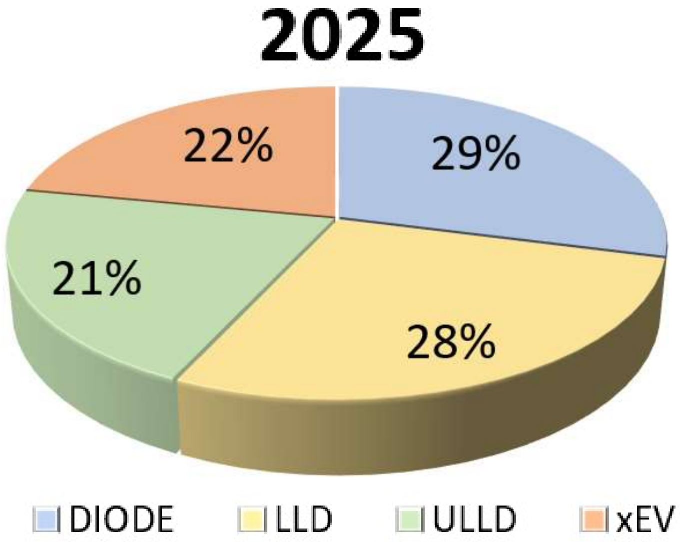
Amount：NT$ Million	1Q2026		4Q2025		1Q2025		1Q26 Over 4Q25	1Q26 Over 1Q25
	Amount	%	Amount	%	Amount	%	%	%
Net operating revenue	2,037	100.00	1,840	100.00	2,116	100.00	10.71%	-3.73%
Operating costs	1,488	73.05	1,352	73.48	1,507	71.22	10.06%	-1.26%
Gross profit	549	26.95	488	26.52	609	28.78	12.50%	-9.85%
Operating expenses	419	20.57	428	23.26	370	17.49	-2.10%	13.24%
Operating income	130	6.38	60	3.26	239	11.29	116.67%	-45.61%
Non-operating income and expenses	40	1.96	66	3.59	69	3.26	-160.61%	-42.03%
Profit before tax	170	8.35	126	6.85	308	14.56	34.92%	-44.81%
Net profit attributable to: Owners of the parent company	173	8.49	170	9.24	236	11.15	1.76%	-26.69%
EPS(NT$)	1.70		1.67		2.32		1.80%	-26.72%

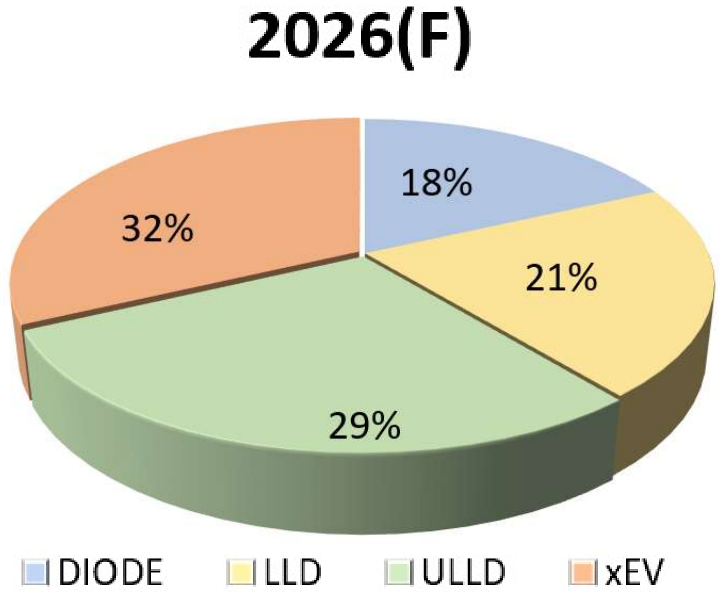
Financial Highlight



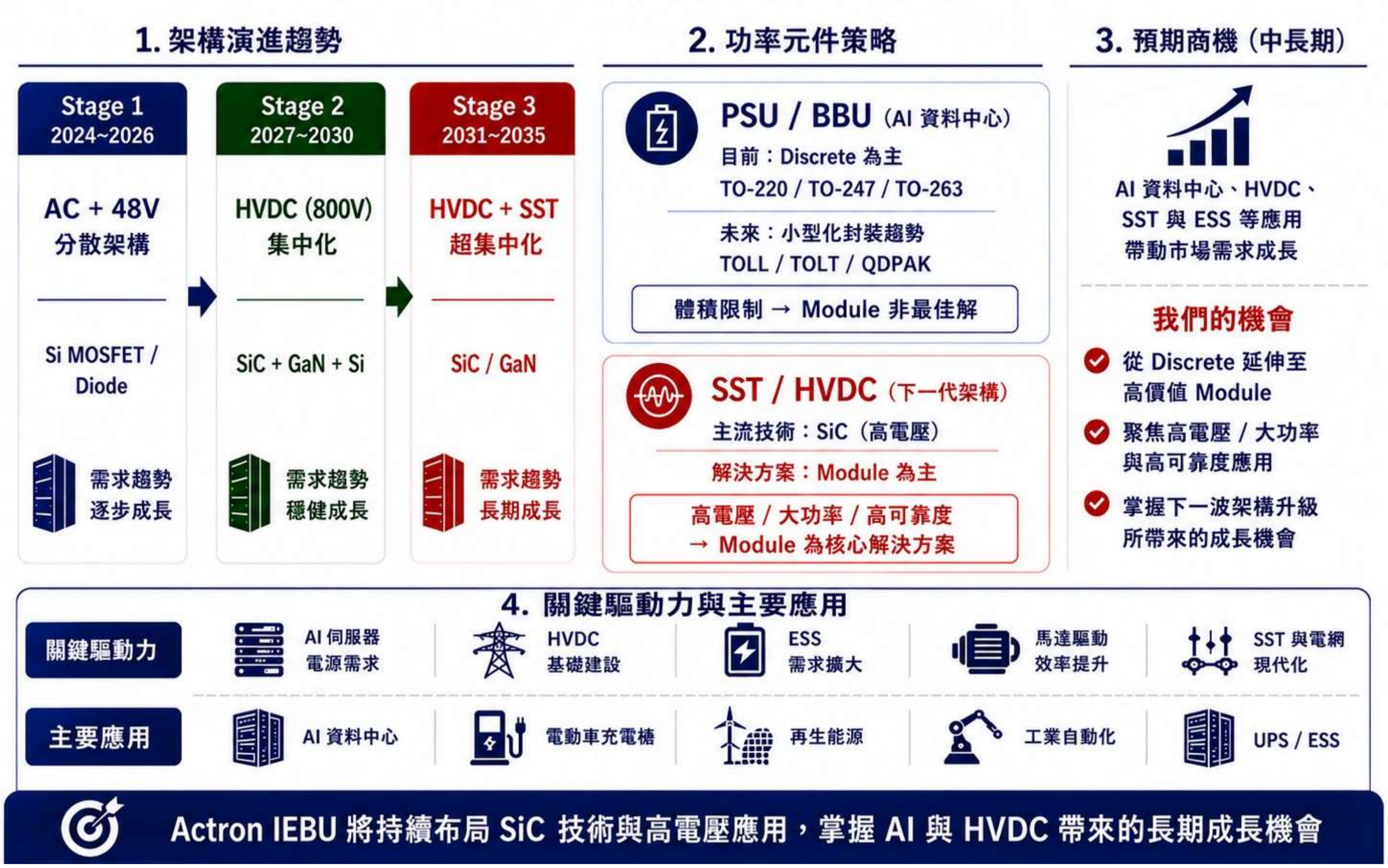


Sales Contribution by Products





Actron AI 電源戰略：掌握 HVDC / SST 長期成長商機



1. 架構演進趨勢

Stage 1 2024~2026	Stage 2 2027~2030	Stage 3 2031~2035
AC + 48V 分散架構	HVDC (800V) 集中化	HVDC + SST 超集中化
Si MOSFET / Diode	SiC + GaN + Si	SiC / GaN
需求趨勢 逐步成長	需求趨勢 穩健成長	需求趨勢 長期成長

2. 功率元件策略

PSU / BBU (AI 資料中心)

目前：Discrete 為主

TO-220 / TO-247 / TO-263

未來：小型化封裝趨勢

TOLL / TOLT / QDPAK

體積限制 → Module 非最佳解

SST / HVDC (下一代架構)

主流技術：SiC（高電壓）

解決方案：Module 為主

高電壓 / 大功率 / 高可靠度
→ Module 為核心解決方案

3. 預期商機 (中長期)

AI 資料中心、HVDC、
SST 與 ESS 等應用
帶動市場需求成長

我們的機會

- ✓ 從 Discrete 延伸至高價值 Module
- ✓ 聚焦高電壓 / 大功率與高可靠度應用
- ✓ 掌握下一波架構升級所帶來的成長機會

4. 關鍵驅動力與主要應用

關鍵驅動力	AI 伺服器 電源需求	HVDC 基礎建設	ESS 需求擴大	馬達驅動 效率提升	SST 與電網 現代化
主要應用	AI 資料中心	電動車充電樁	再生能源	工業自動化	UPS / ESS

Actron IEBU 將持續布局 SiC 技術與高電壓應用，掌握 AI 與 HVDC 帶來的長期成長機會

Complete Power Semiconductor Portfolio

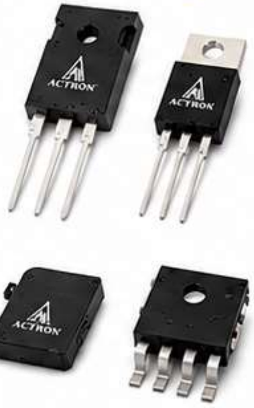
Power Module–Focused Solutions for AI-HVDC, PSU & Industrial Systems

ACTRON®

POWER DISCRETE
Si / SiC / GaN

Standard & Advanced Packages

- TO-247
- TOLL
- TOLT*
- QDPAK*



*In Development

Optimized for efficiency, thermal performance & compact design

POWER MODULE – CORE FOR AI & HVDC SYSTEMS

INDUSTRIAL PLATFORMS

AEA
(Easy 1B)

Cost-effective, reliable

AEB
(Easy 2B)

High performance, low inductance

A62
(62mm)

High power / high current

ADP
(ED3)

Compact, standard platform

AUTOMOTIVE PLATFORMS

AEP
(HPD)

High power density

ATS

Compact, thermal optimized

Optimized for AI Power Systems

High Efficiency × High Power Density × High Reliability

AI-HVDC | PSU | BBU | SST | ESS | Motor Drive

INTEGRATED POWER MODULE (IPM)

SD DIP
(Super Mini DIP)

Compact integrated solution

MD DIP
(Mini DIP)

For motor & industrial control

Compact integrated solution for motor & industrial control

Wide Voltage Coverage
650V → 3300V+

Power Module Focus
for AI-HVDC & PSU

Discrete + Module
Complete Solution

Automotive-Grade
Reliability

Q & A